

| Ref # | Hits | Search Query | DBs   | Default Operator | Plurals | Time Stamp       |
|-------|------|--------------|---|------------------|---------|------------------|
| L1    | 12   | 438/118-119  | US-PGPUB;<br>USPAT;<br>EPO; JPO                                   | OR               | ON      | 2005/06/17 08:12 |
| L2    | 2270 | 438/118      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/06/17 08:12 |
| L3    | 736  | 438/119      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/06/17 08:13 |
| L4    | 1018 | 257/782      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/06/17 08:13 |
| L5    | 1648 | 257/783      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/06/17 08:13 |
| L6    | 405  | 219/635      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/06/17 08:14 |
| L7    | 182  | 219/603      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/06/17 08:14 |
| L8    | 75   | 219/616      | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR               | ON      | 2005/06/17 08:14 |

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| L9  | 70   | 219/651  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 08:14 |
| L10 | 74   | 219/673  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 08:14 |
| L11 | 102  | 219/677  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 08:14 |
| L12 | 4927 | 2 3 4 5 6 7 8 9 10 11  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 08:14 |
| L13 | 510  | 12 and (induct\$3 near3 heat\$3)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 08:16 |
| L14 | 53   | 13 and (solder eutectic)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 08:16 |
| L15 | 12   | 13 and ((chip die (semiconductor<br>near1 (component device element<br>package)) dice) with (substrate<br>carrier pcb board))  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 08:18 |
| L16 | 0    | ("5558795").URPN.  | USPAT   | OR | ON | 2005/06/17 08:33 |
| L17 | 15   | ("3706176"   "3781978"  <br>"3783218"   "3872275"  <br>"4069498"   "4079511"  <br>"4154998"   "4224494"  <br>"4251852"   "4380484"  <br>"4552300"   "4740663"  <br>"4757175"   "4814943"  <br>"5182424").PN. | US-PGPUB;<br>USPAT;<br>USOCR                                      | OR | ON | 2005/06/17 08:33 |

| Ref # | Hits | Search Query  | DBs  | Default Operator | Plurals | Time Stamp       |
|-------|------|---|--|------------------|---------|------------------|
| L1    | 29   | (US-6288376-\$ or US-6386422-\$ or US-6686565-\$ or US-5573688-\$ or US-5520320-\$ or US-5193735-\$ or US-5066850-\$ or US-4817851-\$ or US-4750664-\$ or US-4568277-\$ or US-5785233-\$ or US-5440101-\$ or US-5433368-\$ or US-5154338-\$ or US-4938410-\$ or US-6138893-\$ or US-5524810-\$ or US-5345061-\$ or US-5338008-\$ or US-5230460-\$ or US-6135344-\$ or US-4983804-\$ or US-6275750-\$ or US-6423945-\$ or US-5409543-\$ or US-4687895-\$).did. or (US-5492265-\$ or US-6794275-\$ or US-6608291-\$).did. | USPAT  | OR               | ON      | 2005/06/17 14:07 |
| L2    | 8    | 1 and ceramic   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/06/17 14:13 |
| L3    | 0    | "6608291".pn. and ceramic   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/06/17 14:29 |
| L4    | 445  | (hot near plate) near3 (ceramic alumina (aluminum adj nitride))   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/06/17 14:30 |
| L5    | 3273 | (die near1 (attachment attached attach bonded bond bonding)) near3 (method process)   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/06/17 14:18 |
| L6    | 1    | 4 and 5   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR               | ON      | 2005/06/17 14:18 |

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| L7  | 18904 | ((die dice chip) near3 (attachment attached attach bonded bond bonding)) near4 (carrier substrate)                          | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 14:18 |
| L8  | 3     | 4 and 7   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 14:20 |
| L9  | 24879 | ((die dice chip) near3 (attachment attached attach bonded bond bonding soldering soldered)) near4 (carrier board substrate) | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 14:45 |
| L10 | 4     | 4 and 9   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 14:22 |
| L11 | 55388 | (induct\$3 near1 heat\$3)   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 14:21 |
| L12 | 19    | 4 and 11  | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 14:22 |
| L13 | 1     | 4 with (semiconductor chip die) with (bond\$3 attach\$3)  | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 14:31 |
| L14 | 508   | (hot near plate) near4 (ceramic alumina (aluminum adj nitride))   | US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/06/17 14:30 |

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| L15 | 84  | 14 with (semiconductor chip die)   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 14:44 |
| L16 | 54  | 15 and solder and (substrate carrier board)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 14:35 |
| L17 | 30  | 14 and (heating with (furnace tunnel system))  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 14:36 |
| L18 | 201 | 14 and (semiconductor chip die)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 14:44 |
| L19 | 157 | 18 and (attachment attached attach bonded bond bonding soldering soldered)                                   | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 14:45 |
| L20 | 32  | 18 and ((attachment attached attach bonded bond bonding soldering soldered) near4 (carrier board substrate)) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 14:46 |
| L21 | 2   | 18 and (reflow near3 soldering)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 14:47 |
| L22 | 2   | 14 and (reflow near3 soldering)  | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 14:48 |

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| L23 | 7 | 14 and (heating near zone) | US-PGPUB;<br>USPAT;<br>USOCR;<br>EPO; JPO;<br>DERWENT;<br>IBM_TDB | OR | ON | 2005/06/17 14:48 |
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